

Claims

1. A method of manufacturing a polishing pad for polishing substrates, the method including:

providing a foundation layer having a surface, the surface having a pattern of protrusions formed on the surface, the protrusions having upper surfaces and side walls; and

forming a polishing surface layer above the foundation layer;

the forming of the polishing surface layer including forming a non-continuous polishing surface layer, the non-continuous surface layer being attached to the foundation layer, and comprising discrete portions, each discrete portion being attached to an upper surface of one corresponding protrusion on the foundational layer;

the polishing surface layer being formed along with the foundation layer in a double molding process; and

the forming of the polishing surface layer including mixing a set of polymerizable materials with a plurality of porogens, and forming a plurality of closed cell pores within the polishing surface layer.

2. The method according to claim 1, further including:

removing the polishing surface layer from the foundation layer; and

forming a second polishing surface layer above the foundation layer.

3. The method according to claim 1, wherein the providing of the foundation layer includes first removing a previously formed polishing surface layer from the foundation layer.